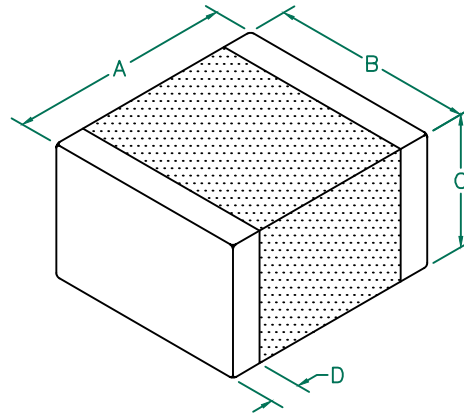


# HI2220P601R-10

## PHYSICAL DIMENSIONS:

A	5.59 [.220]	+ 0.51 [.020]
B	5.08 [.200]	+ 0.25 [.010]
C	3.05 [.120]	+ 0.25 [.010]
D	0.76 [.030]	+ 0.25 [.010]



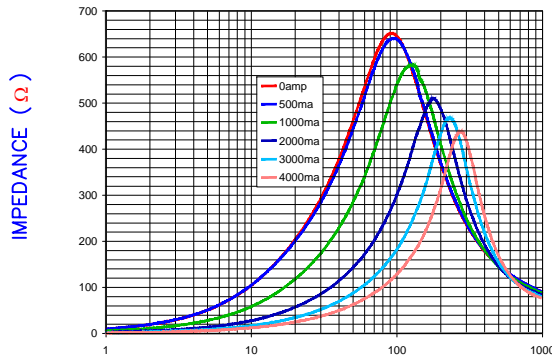
## ELECTRICAL CHARACTERISTICS:

	Z @ 100MHz ( $\Omega$ )	DCR ( $\Omega$ )	Rated Current
Nominal	600		
Minimum	450		
Maximum	750	0.025	4000 mA

NOTES: UNLESS OTHERWISE SPECIFIED

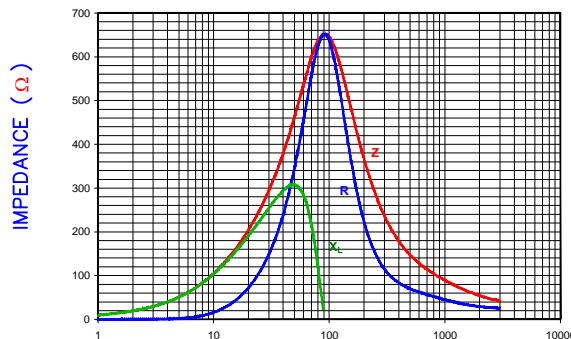
1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 13" REELS, 2,000 PCS/REEL.
2. U.S. PATENT 5,821,846 AND 6,107,907 ARE APPLIED.
3. TERMINATION FINISH IS 100% TIN.
4. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
5. OPERATEING TEMPERATURE TEMP:  $-40^{\circ}\text{C} \sim +125^{\circ}\text{C}$  (INCLUDING SELF-HEATING)

Z vs FREQUENCY  
IMPEDANCE UNDER DC BIAS



FREQUENCY (MHz)

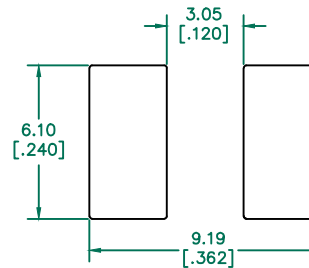
|Z|, R, AND X vs. FREQUENCY



FREQUENCY (MHz)

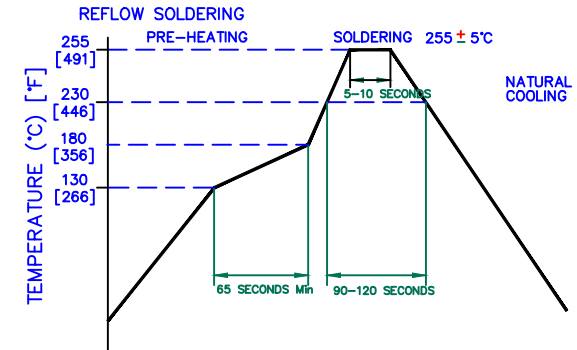
Z R X<sub>L</sub>

## LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 (0.30) to this dimension.)

## RECOMMENDED SOLDERING CONDITIONS



DIMENSIONS ARE IN mm [INCHES]				This print is the property of Laird Tech. and is loaned in confidence subject to return upon request and with the understanding that no copies shall be made without the written consent of Laird Tech. All rights to design or invention are reserved.	
F	UPDATE NOTE 2	05/14/15	QU	PROJECT/PART NUMBER: <b>HI2220P601R-10</b>	
E	ADD OPERATING TEMPERATURE UPDATE LAIRD LOGO AND REFLOW CURVE	08/05/13	QU		
D	UPDATE COMPANY LOGO ADD ROHS	01/24/08	JRK	REV	PART TYPE:
C	CHANGE C DIMENSION FROM .130	05/11/04	JRK	F	CO-FIRE
B	ADD DC BIAS CURVE, CHG DCR RATING	03/19/03	JRK	DATE:	SCALE:
A	ORIGINAL DRAFT	01/12/01	BAC	01/12/01	NTS
REV	DESCRIPTION	DATE	INT	CAD #	SHEET:
				HI2220P601R-10-F	TOOL #
					1 of 1

